

# 1 MEG (65536 words × 16 bits) DRAM Fast Page Mode, Byte Write

#### Overview

The LC321664AJ, AM, AT is a CMOS dynamic RAM operating on a single 5 V power source and having a 65536-word × 16-bit configuration. Equipped with large capacity capabilities, high-speed transfer rates and low power dissipation, this series is suited for a wide variety of applications ranging from computer main memory and expansion memory to commercial equipment.

Address input utilizes a multiplexed address bus which permits it to be enclosed in compact plastic packages of SOJ 40-pin, SOP 40-pin and TSOP 44-pin. Refresh rates are within 4 ms with 256 row address (A0 to A7) selection and support RAS-only refresh, CAS-before-RAS refresh and hidden refresh settings.

There are functions such as page mode, read-modify-write, and byte-write.

#### **Features**

- 65536-word × 16-bit configuration
- Single 5 V  $\pm 10\%$  power supply
- All input and output (I/O) TTL compatible
- Supports fast page mode, read-modify-write, and byte-write.
- Supports output caching control using early write and Output Enable (OE) control.
- 4 ms refresh using 256 refresh cycles
- Supports RAS-only refresh, CAS-before-RAS refresh and hidden refresh.
- Packages
   SOJ 40-pin (400 mil) plastic package: LC321664AJ

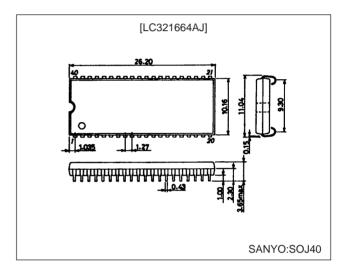
SOP 40-pin (525 mil) plastic package: LC321664AM TSOP 44-pin (400 mil) plastic package: LC321664AT

• RAS access time/column address access time/CAS access time/ cycle time/power dissipation

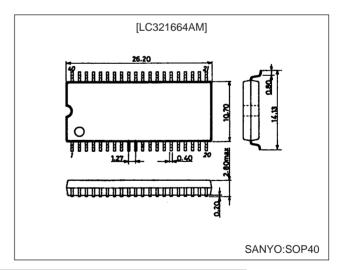
#### **Package Dimensions**

unit: mm

#### 3200-SOJ40



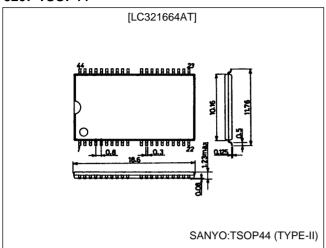
unit : mm 3195-SOP40



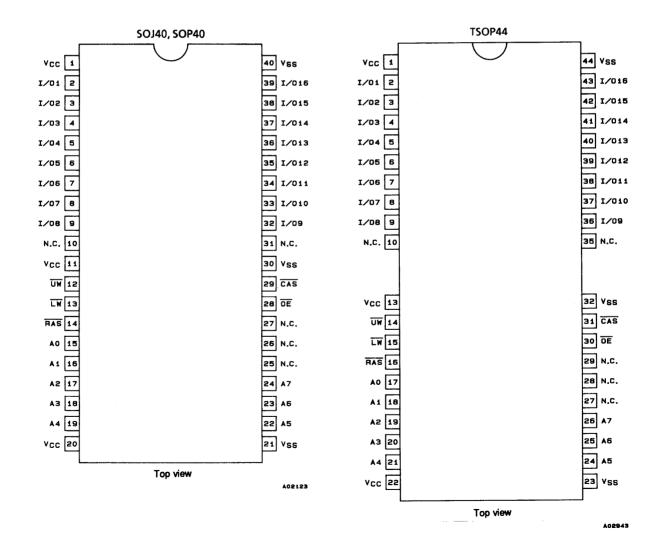
Parameter		LC321664AJ, AM, AT-80		
RAS access time		80 ns		
Column address access time		45 ns		
CAS access time		30 ns		
Cycle time		135 ns		
Power dissipation	During operation	633 mW		
(max.)	During standby	5.5 mW (CMOS level)/11 mW (TTL level)		

# **Package Dimensions**

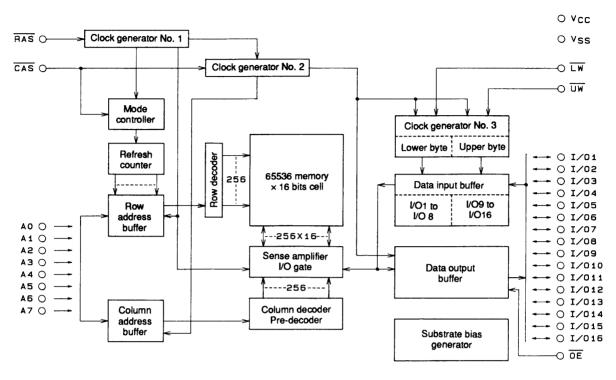
unit : mm **3207-TSOP44** 



#### **Pin Assignments**



#### **Block Diagram**



A02125

# **Specifications**

#### **Absolute Maximum Ratings**

Parameter	Symbol	Symbol Ratings		Note	
Maximum supply voltage		V <sub>CC</sub> max	-1.0 to +7.0	V	1
Input voltage		V <sub>IN</sub>	-1.0 to +7.0	V	1
Output voltage		V <sub>OUT</sub>	-1.0 to +7.0	V	1
Allowable power dissipation	LC321664AJ, AM	Pd max	800	mW	1
	LC321664AT	Fulliax	700	1111	'
Output short-circuit current		I <sub>OUT</sub>	50	mA	1
Operating temperature range		Topr	0 to +70	°C	1
Storage temperature range		Tstg	-55 to +150	°C	1

Note: 1) Stresses greater than the above listed maximum values may result in damage to the device.

#### DC Recommended Operating Ranges at Ta = 0 to $+70^{\circ}$ C

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Parameter	Symbol	min	typ	max	Unit	Note
Power supply voltage	V <sub>CC</sub>	4.5	5.0	5.5	V	2
Input high level voltage	V <sub>IH</sub>	2.4		6.5	V	2
Input low level voltage (A0 to A7, RAS, CAS, UW, LW, OE)	V <sub>IL</sub>	-1.0*		+0.8	V	2
Input low level voltage (I/O1 to I/O16)	V <sub>IL</sub>	-0.5*		+0.8	V	2

Note: 2) All voltages are referenced to  $V_{SS}$ .

A bypass capacitor of about 0.1  $\mu$ F should be connected between  $V_{CC}$  and  $V_{SS}$  of the device.

\* -2.0 V when pulse width is less than 20 ns

# DC Electrical Characteristics at $Ta=0~to+70^{\circ}C,\,V_{CC}$ = 5 $V\pm10\%$

Parameter	Symbol	Conditions	min	max	Unit	Note
Operating current (Average current during operation)	I <sub>CC1</sub>	$\overline{RAS}$ , $\overline{CAS}$ , address cycling: $t_{RC} = t_{RC}$ min		115	mA	3, 4, 5
Standby current	I <sub>CC2</sub>	$\overline{RAS} = \overline{CAS} = V_{IH}$		2	mA	
RAS-only refresh current	I <sub>CC3</sub>	$\overline{RAS}$ cycling, $\overline{CAS} = V_{IH}$ : $t_{RC} = t_{RC}$ min		115	mA	3, 5
Fast page mode current	I <sub>CC4</sub>	$\overline{RAS} = V_{IL}$ , $\overline{CAS}$ address cycling: $t_{PC} = t_{PC}$ min		70	mA	3, 4, 5
Standby current	I <sub>CC5</sub>	$\overline{RAS} = \overline{CAS} = V_{CC} - 0.2V$		1	mA	
CAS-before-RAS refresh current	I <sub>CC6</sub>	$\overline{RAS}$ , $\overline{CAS}$ cycling: $t_{RC} = t_{RC}$ min		115	mA	3
Input leakage current	I <sub>IL</sub>	$0V \le V_{IN} \le 6.5V$ , pins other than measuring pin = $0V$	-10	+10	μA	
Output leakage current	I <sub>OL</sub>	$D_{OUT}$ disable, $0V \le V_{OUT} \le 5.5V$	-10	+10	μA	
Output high level voltage	V <sub>OH</sub>	I <sub>OUT</sub> = -2.5mA	2.4		V	
Output low level voltage	V <sub>OL</sub>	I <sub>OUT</sub> = 2.1mA		0.4	V	

Note: 3) All current values are measured at minimum cycle rate. Since current flows immoderately, if cycle time is longer than shown here value becomes smaller.

<sup>4)</sup>  $I_{CC1}$  and  $I_{CC4}$  are dependent on output loads. Maximum values for  $I_{CC1}$  and  $I_{CC4}$  represent values with output open.

<sup>5)</sup> One address change can be performed while  $\overline{RAS} = V_{IL}$  ( $I_{CC1}$  and  $I_{CC3}$ ). One address change can be performed during one  $t_{PC}$  cycle ( $I_{CC4}$ ).

# AC Electrical Characteristics at Ta=0 to $+70^{\circ}C$ , $V_{CC}=5$ V $\pm$ 10% (Note 6, 7, 8)

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Parameter	Symbol	min	max	Unit	Note
Random read or write cycle time	t <sub>RC</sub>	135		ns	
Read-write/read-modify-write cycle time	t <sub>RWC</sub>	180		ns	
Fast page mode cycle time	t <sub>PC</sub>	55		ns	
Fast page mode Read-write/read-modify- write cycle time	t <sub>PRWC</sub>	100		ns	
RAS access time	t <sub>RAC</sub>		80	ns	9, 14 15
CAS access time	t <sub>CAC</sub>		30	ns	9, 14
Column address access time	t <sub>AA</sub>		45	ns	9, 15
CAS precharge access time	t <sub>CPA</sub>		50	ns	9
Output low-impedance time from CAS low	t <sub>CLZ</sub>	0		ns	9
Output buffer turn-off delay time	t <sub>OFF</sub>	0	20	ns	10
Rise or fall time	t <sub>T</sub>	3	50	ns	
RAS precharge time	t <sub>RP</sub>	45		ns	
RAS pulse width	t <sub>RAS</sub>	80	10000	ns	
RAS pulse width for fast page mode only	t <sub>RASP</sub>	80	100000	ns	
RAS hold time	t <sub>RSH</sub>	30		ns	
CAS hold time	t <sub>CSH</sub>	80		ns	
CAS pulse width	t <sub>CAS</sub>	30	10000	ns	
RAS to CAS delay time	t <sub>RCD</sub>	25	50	ns	14
RAS to column address delay time	t <sub>RAD</sub>	17	35	ns	15
CAS to RAS precharge time	t <sub>CRP</sub>	10		ns	
CAS precharge time	t <sub>CP</sub>	10		ns	
Row address setup time	t <sub>ASR</sub>	0		ns	
Row address hold time	t <sub>RAH</sub>	12		ns	
Column address setup time	t <sub>ASC</sub>	0		ns	
Column address hold time	t <sub>CAH</sub>	20		ns	
Column address hold time referenced to RAS	t <sub>AR</sub>	60		ns	
Column address to RAS lead time	t <sub>RAL</sub>	45		ns	
Read command setup time	t <sub>RCS</sub>	0		ns	
Read command hold time referenced to CAS	t <sub>RCH</sub>	0		ns	11
Read command hold time referenced to RAS	t <sub>RRH</sub>	0		ns	11
Write command hold time	t <sub>WCH</sub>	15		ns	
Write command hold time referenced to RAS	t <sub>WCR</sub>	60		ns	
Write command pulse width	t <sub>WP</sub>	15		ns	

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Parameter	Symbol	min	max	Unit	Note
Write command to RAS lead time	t <sub>RWL</sub>	20		ns	
Write command to CAS lead time	t <sub>CWL</sub>	20		ns	
Data input setup time	t <sub>DS</sub>	0		ns	12
Data input hold time	t <sub>DH</sub>	20		ns	12
Data input hold time referenced to RAS	t <sub>DHR</sub>	60		ns	
Refresh period	t <sub>REF</sub>		4	ms	
Write command setup time	t <sub>WCS</sub>	0		ns	13
CAS to UW, LW delay time	t <sub>CWD</sub>	50		ns	13
RAS to UW, LW delay time	t <sub>RWD</sub>	100		ns	13
Column address to UW, LW delay time	t <sub>AWD</sub>	65		ns	13
CAS precharge to UW, LW delay time (fast page mode cycle only)	t <sub>CPWD</sub>	70		ns	13
CAS setup time for CAS-before-RAS refresh	t <sub>CSR</sub>	10		ns	
CAS hold time for CAS-before-RAS refresh	t <sub>CHR</sub>	15		ns	
RAS precharge time to CAS active time	t <sub>RPC</sub>	10		ns	
CAS precharge time for CAS-before-RAS counter test	t <sub>CPT</sub>	40		ns	
RAS hold time referenced to OE	t <sub>ROH</sub>	15		ns	
OE access time	t <sub>OEA</sub>		25	ns	9
OE delay time	t <sub>OED</sub>	15		ns	
OE to output buffer turn-off delay time	t <sub>OEZ</sub>	0	15	ns	10
OE command hold time	t <sub>OEH</sub>	20		ns	
Data input to CAS delay time	t <sub>DZC</sub>	0		ns	16
Data input to OE delay time	t <sub>DZO</sub>	0		ns	16
Masked write setup time	t <sub>MCS</sub>	0		ns	
Masked write hold time referenced to RAS	t <sub>MRH</sub>	0		ns	
Masked write hold time referenced to CAS	t <sub>MCH</sub>	0		ns	

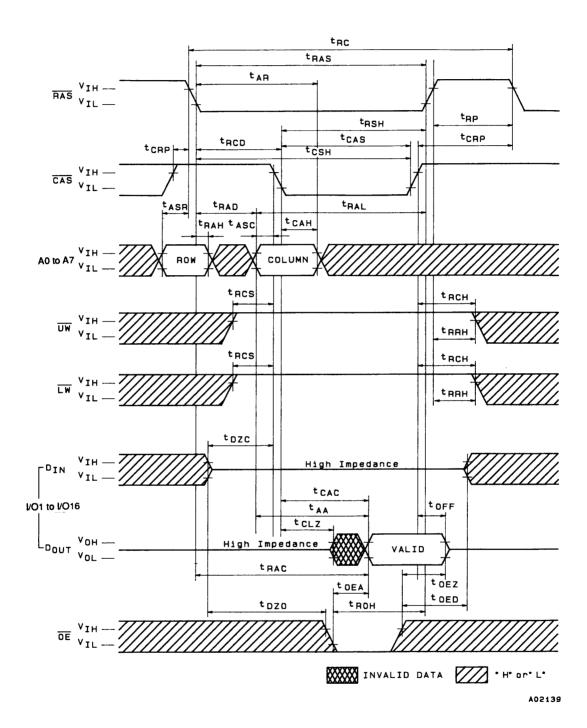
# Input/Output Capacitance at $Ta=25^{\circ}C,\,f$ = 1 MHz, $V_{CC}$ = 5 V $\pm$ 10%

Parameter	Symbol	min	max	Unit
Input capa <u>citance</u> (A <sub>0</sub> to A <sub>7</sub> , RAS, CAS, UW, LW, OE)	C <sub>IN</sub>		7	pF
I/O capacitance (I/O <sub>1</sub> to I/O <sub>16</sub> )	C <sub>I/O</sub>		7	pF

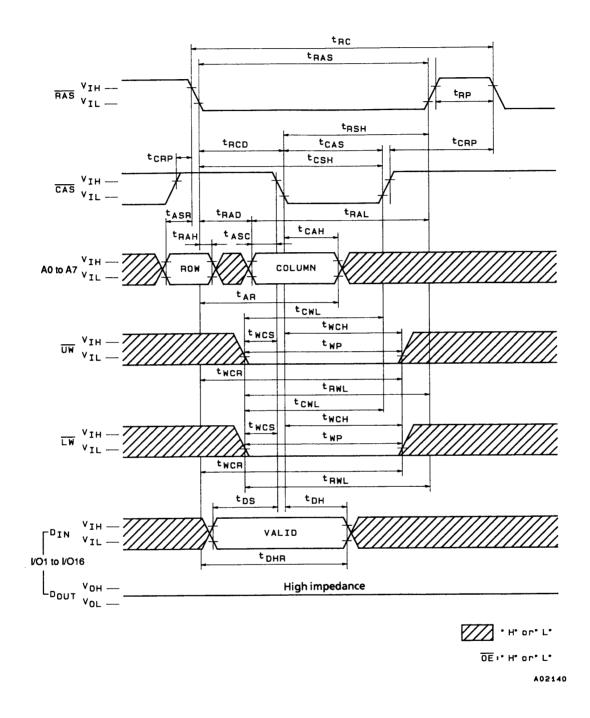
- Notes: 6) After the power is turned on, 200  $\mu$ s are required after the arrival of  $V_{CC}$  stabilized current before memory is initialized and begins operation. In addition, before memory operation initializes, approximately 8 cycles worth of  $\overline{RAS}$  dummy cycles are required. When the on-chip refresh counter is applied, approximately 8-cycles worth of  $\overline{CAS}$ -before- $\overline{RAS}$  dummy cycles are required instead of the  $\overline{RAS}$  dummy cycles.
  - 7) Measured at  $t_T = 5$  ns.
  - 8) When measuring input signal timing,  $V_{IH}$  (min) and  $V_{IL}$  (max) are used for reference points. In addition, rise and fall time are defined between  $V_{IH}$  and  $V_{IL}$ .
  - 9) Measured using an equivalent of 50 pF and one standard TTL load.
  - 10)  $t_{OFF}$  (max) and  $t_{OEZ}$  (max) are defined as the time until output voltage can no longer be measured when output switches to a high impedance condition.
  - 11) Operation is guaranteed if either t<sub>RRH</sub> or t<sub>RCH</sub> are satisfied.
  - 12) These parameters are measured from the falling edge of  $\overline{CAS}$  for an early-write cycle, and from the falling edge of  $\overline{UW}$  and  $\overline{LW}$  for a read-write/read-modify-write cycle.
  - 13)  $t_{WCS}$ ,  $t_{CWD}$ ,  $t_{RWD}$ ,  $t_{AWD}$  and  $t_{CPWD}$  are not restrictive operating parameters for memory in that they specify the operating mode. If  $t_{WCS} \ge t_{WCS}$  (min), the cycle switches to an early-write cycle and output pins switch to high impedance throughout the cycle. If  $t_{CWD} \ge t_{CWD}$  (min),  $t_{RWD} \ge t_{RWD}$  (min),  $t_{AWD} \ge t_{AWD}$  (min) and  $t_{CPWD} \ge t_{CPWD}$  (min), the cycle switches to a read-write/read-modify-write cycle and data outputs equal information in the selected cells. If neither of the above conditions are satisfied, output pins are in an undefined state.
  - 14)  $t_{RCD}$  (max) does not indicate a restrictive operating parameter but instead represents the point at which the access time  $t_{RAC}$  (max) is guaranteed. If  $t_{RCD} \ge t_{RCD}$  (max), access time is determined according to  $t_{CAC}$ .
  - 15)  $t_{RAD}$  (max) does not indicate a restrictive operating parameter but instead represents the point at which the access time  $t_{RAC}$  (max) is guaranteed. If  $t_{RAD} \ge t_{RAD}$  (max), access time is determined according to  $t_{AA}$ .
  - 16) Operation is guaranteed if either t<sub>DZC</sub> or t<sub>DZO</sub> are satisfied.

# **Timing Chart**

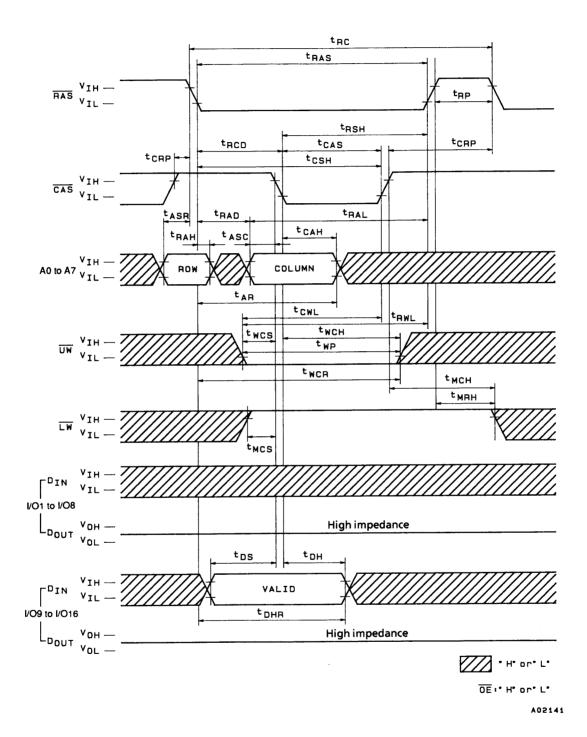
#### **Read Cycle**



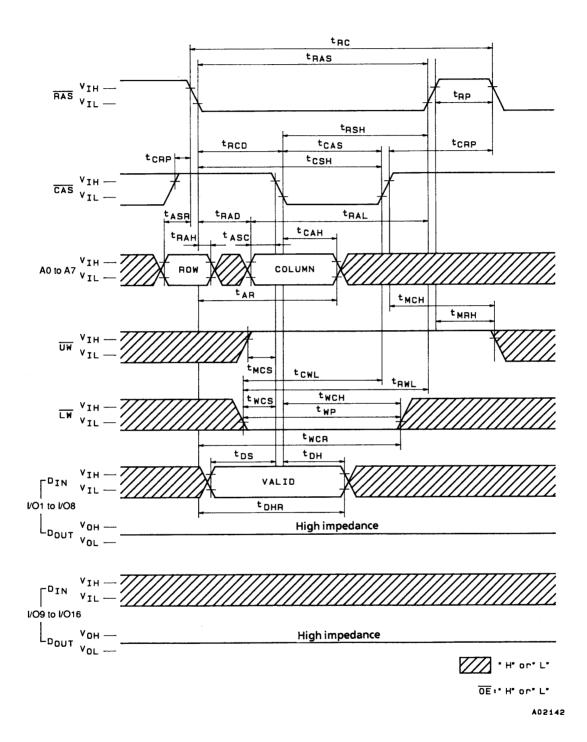
#### **Early Write Cycle**



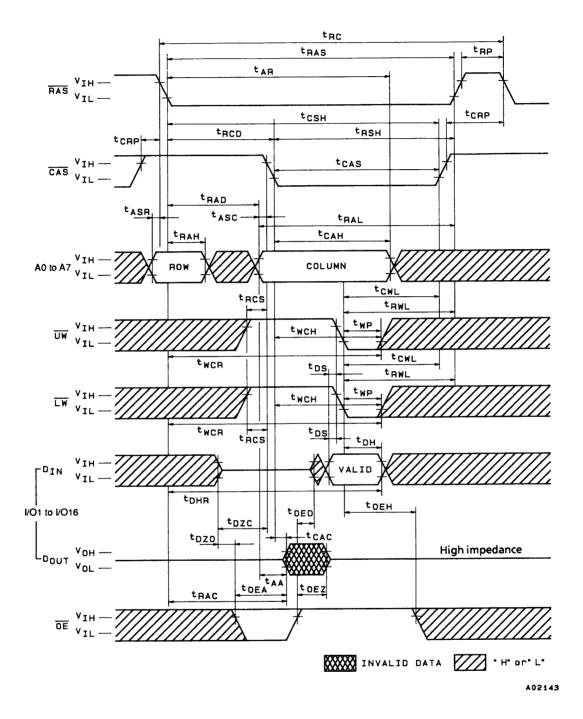
#### **Upper Byte Early Write Cycle**



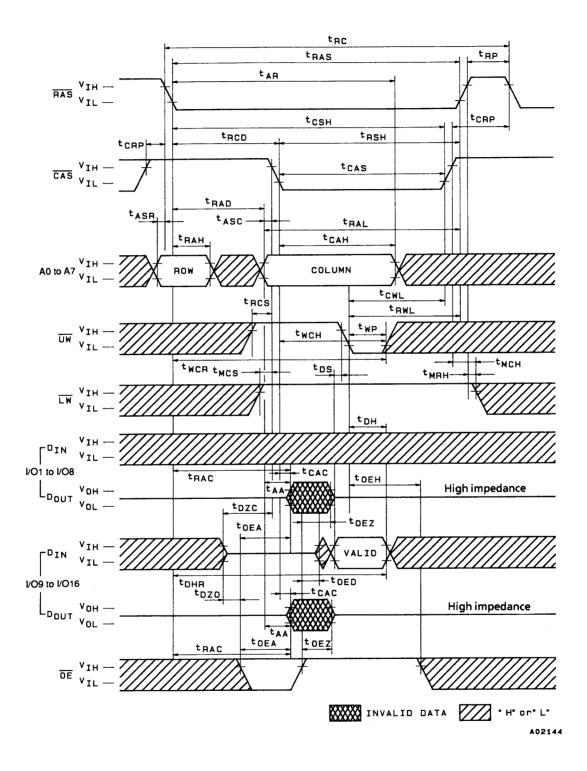
#### **Lower Byte Early Write Cycle**



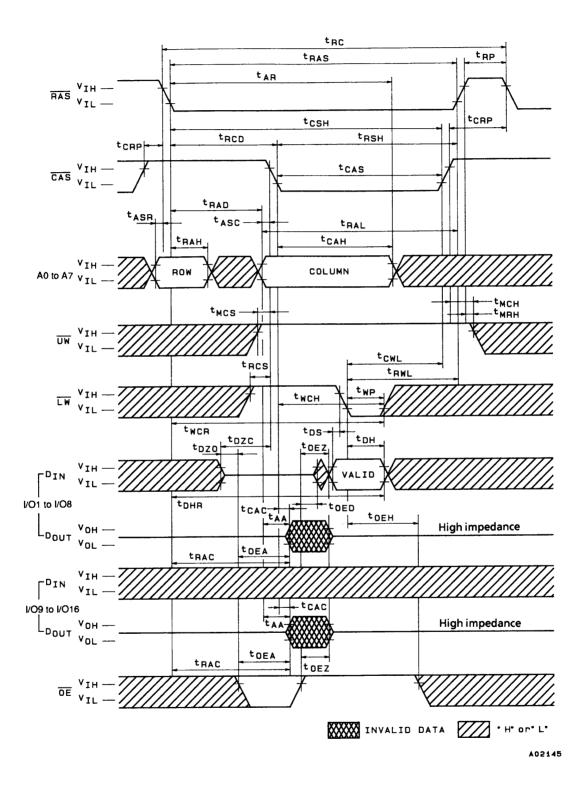
# Write Cycle (OE Control)



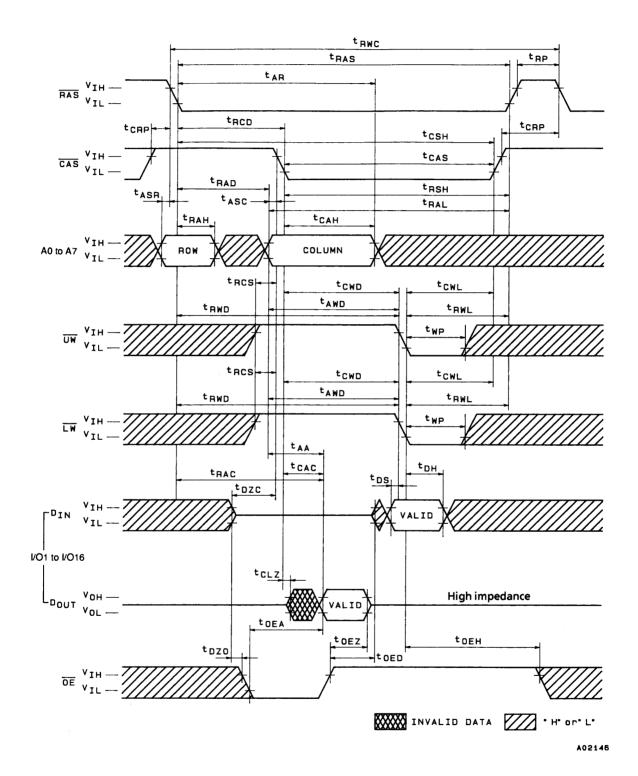
#### **Upper Byte Write Cycle (OE Control)**



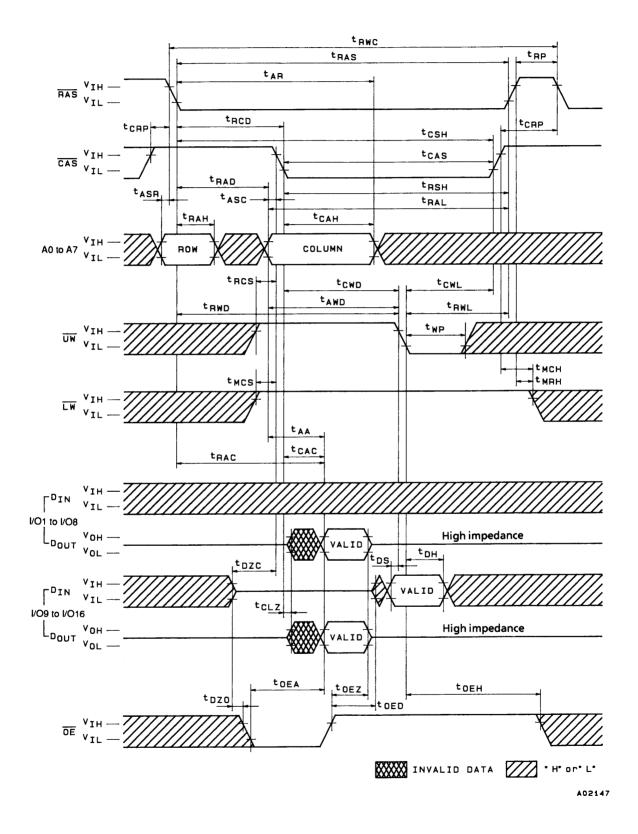
# Lower Byte Write Cycle (OE Control)



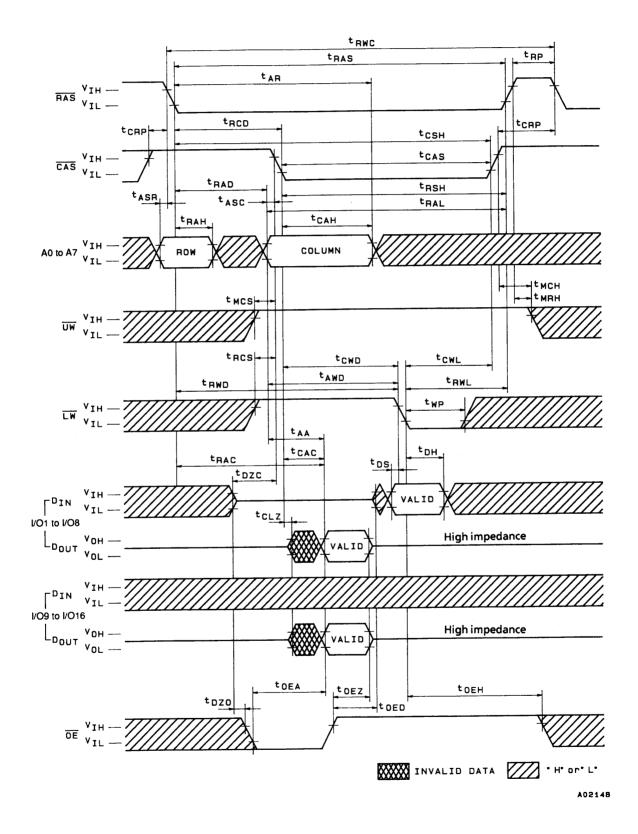
#### **Read-Modify-Write Cycle**



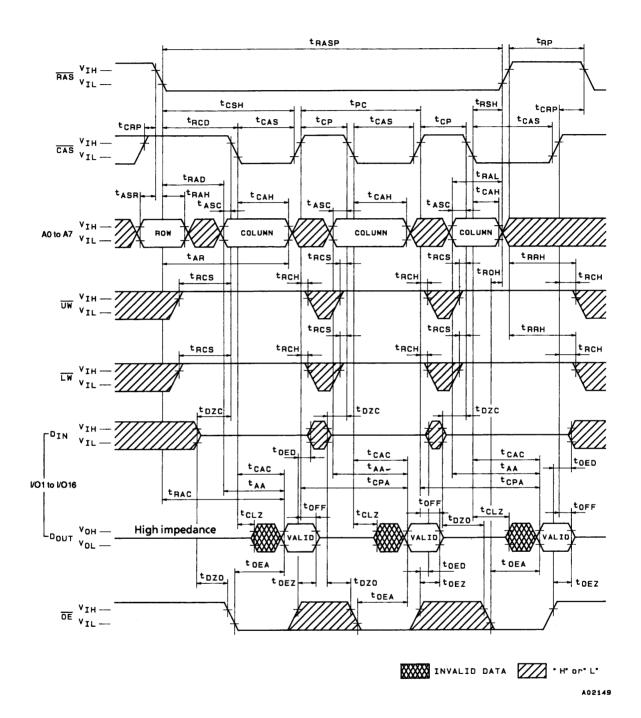
#### **Read-Modify Upper Byte Write Cycle**



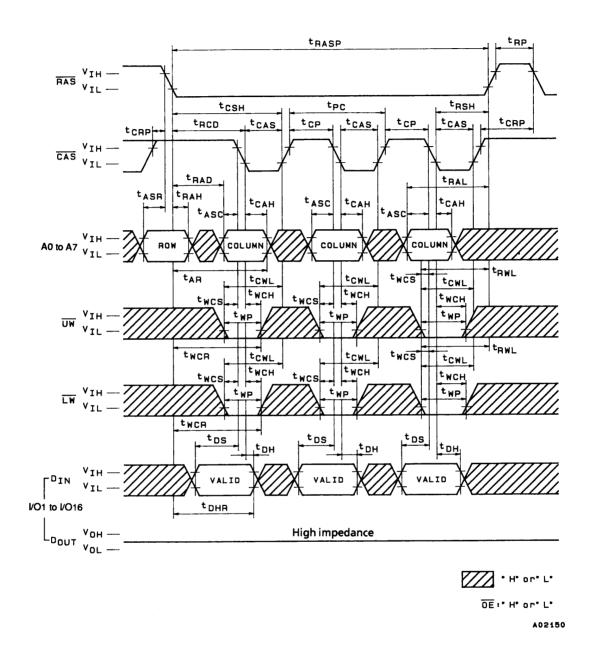
#### **Read-Modify Lower Byte Write Cycle**



#### **Fast Page Mode Read Cycle**

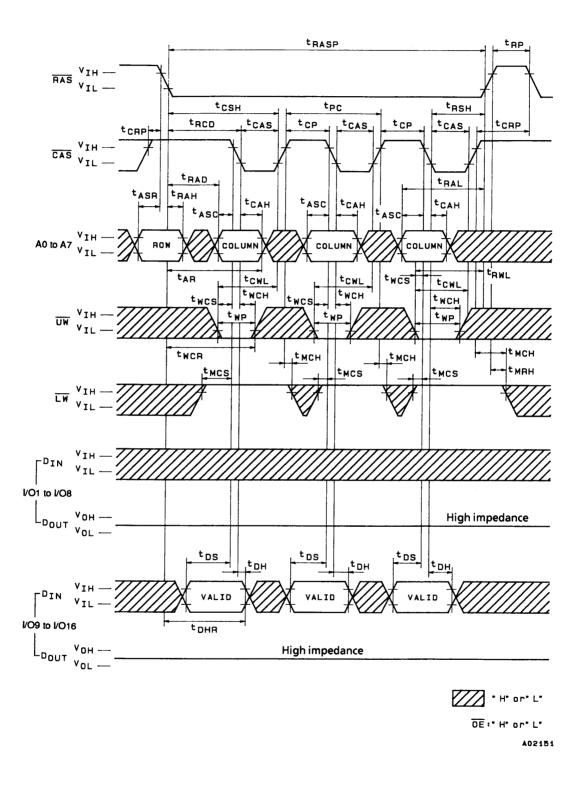


#### **Fast Page Mode Early Write Cycle**

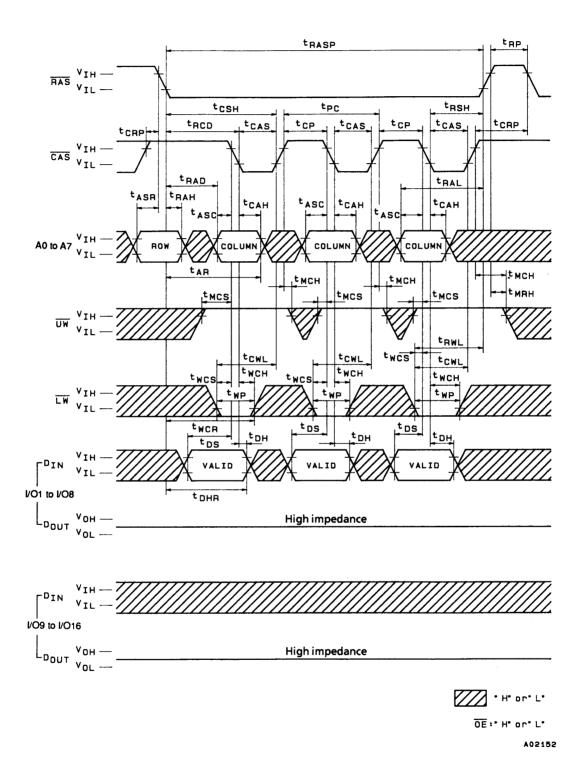


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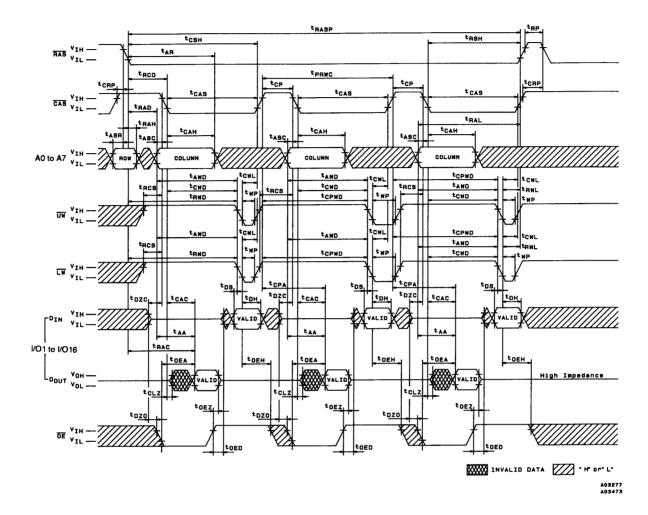
#### Fast Page Mode Upper Byte Early Write Cycle



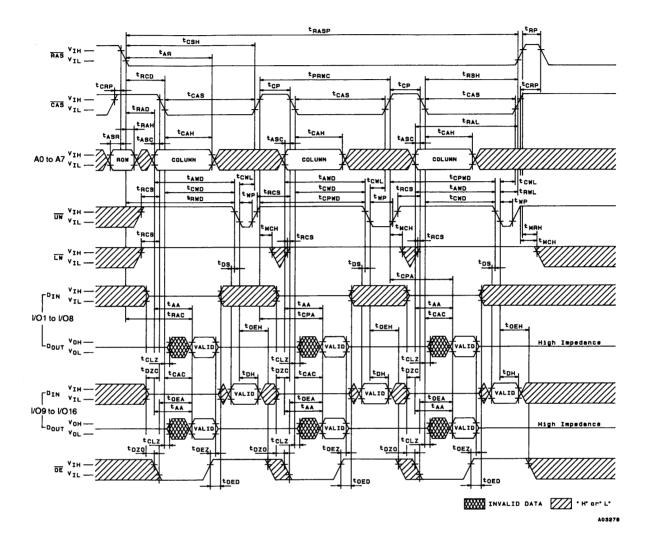
#### Fast Page Mode Lower Byte Early Write Cycle



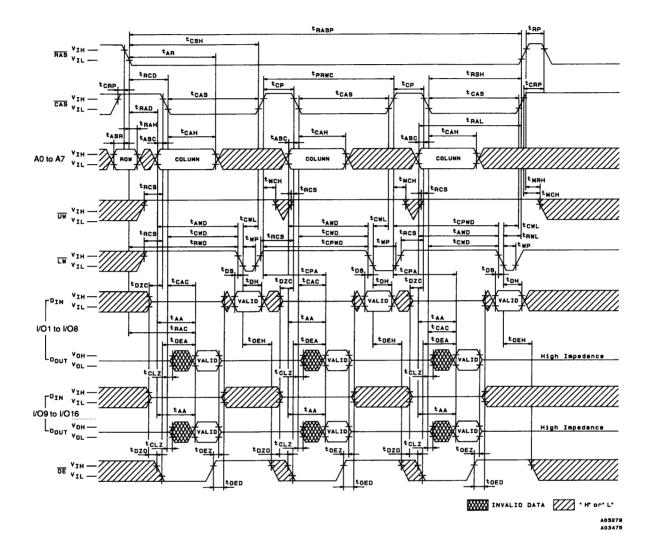
#### Fast Page Mode Read-Modify-Write Cycle



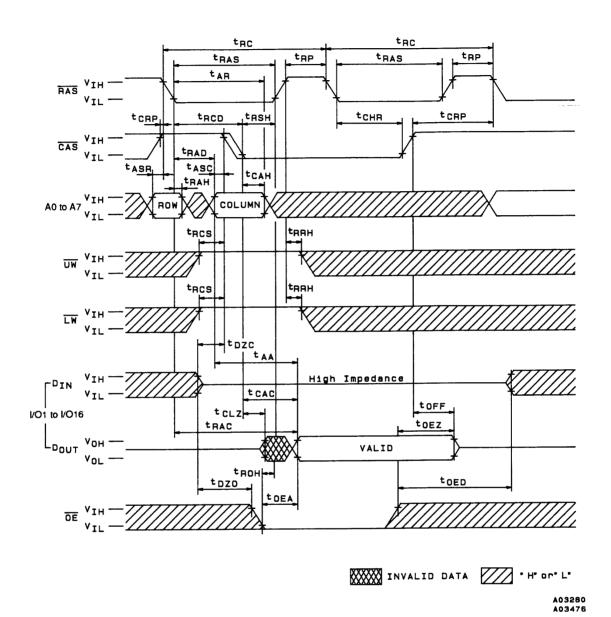
#### Fast Page Mode Read-Modify Upper Byte Write Cycle



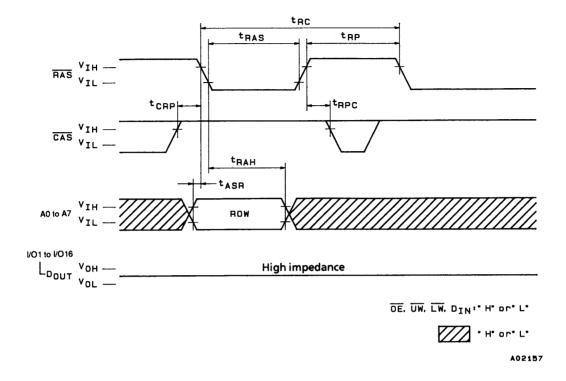
#### Fast Page Mode Read-Modify Lower Byte Write Cycle



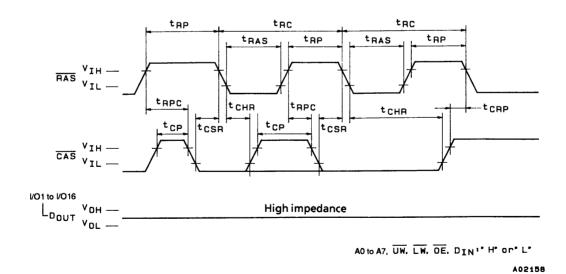
#### **Hidden Refresh Cycle**



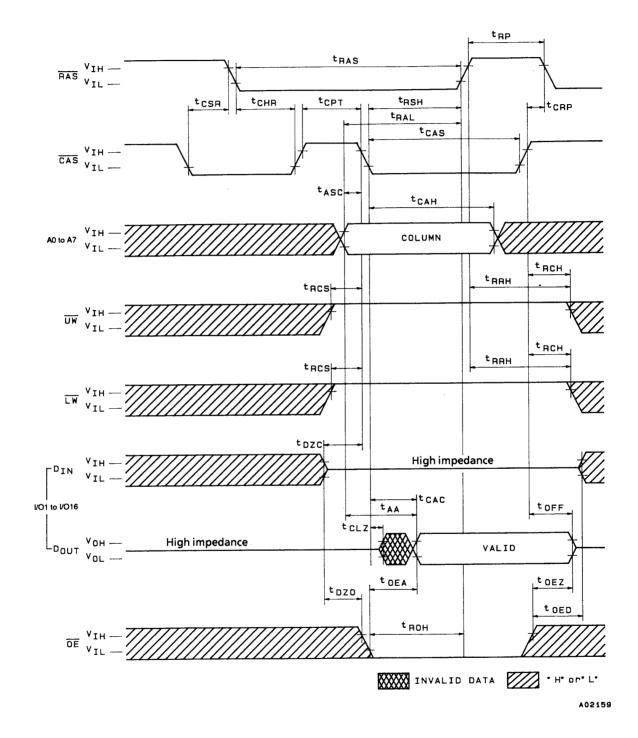
# **RAS-Only Refresh Cycle**



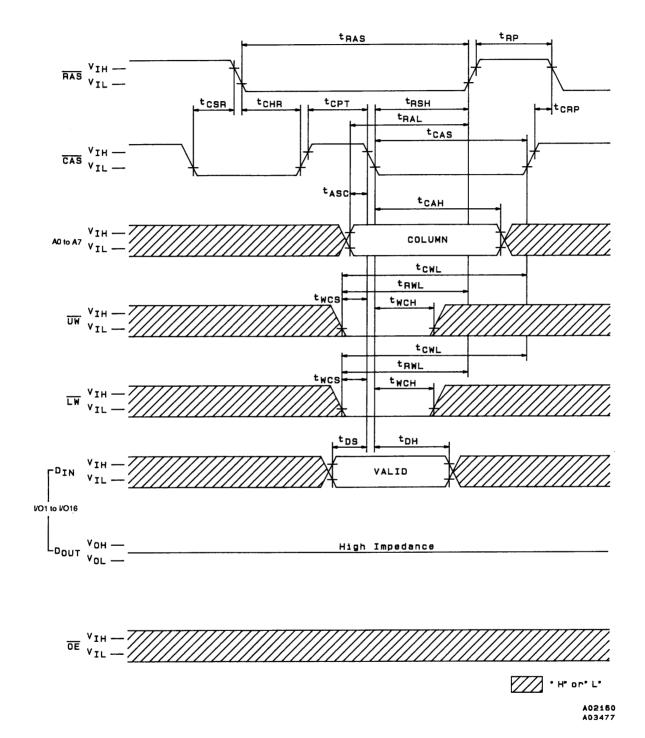
# CAS-Before-RAS Refresh Cycle



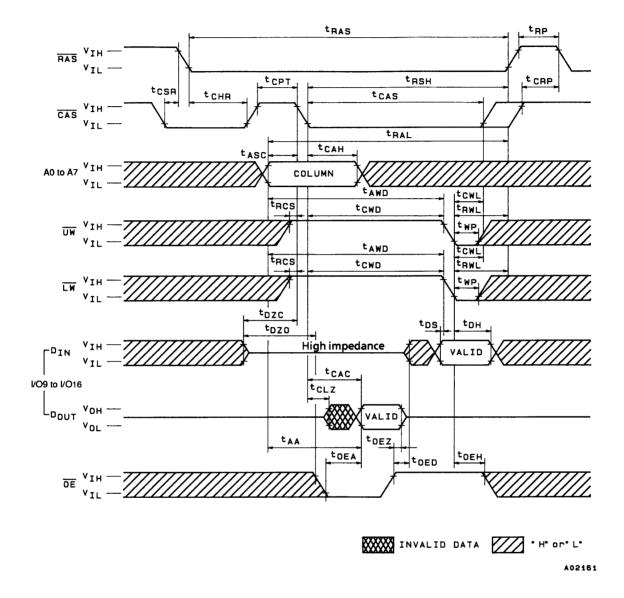
#### **CAS-Before-RAS Refresh Counter Test Cycle (read)**



# CAS-Before-RAS Refresh Counter Test Cycle (write)



# CAS-Before-RAS Refresh Counter Test Cycle (read-modify-write)



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